

Approved by:

Checked by:

Issued by:

# ***SPECIFICATION***

**MODEL: HDF163AN F11**



**SHUOLDER ELECTRONICS LIMITED**

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# 1. SCOPE

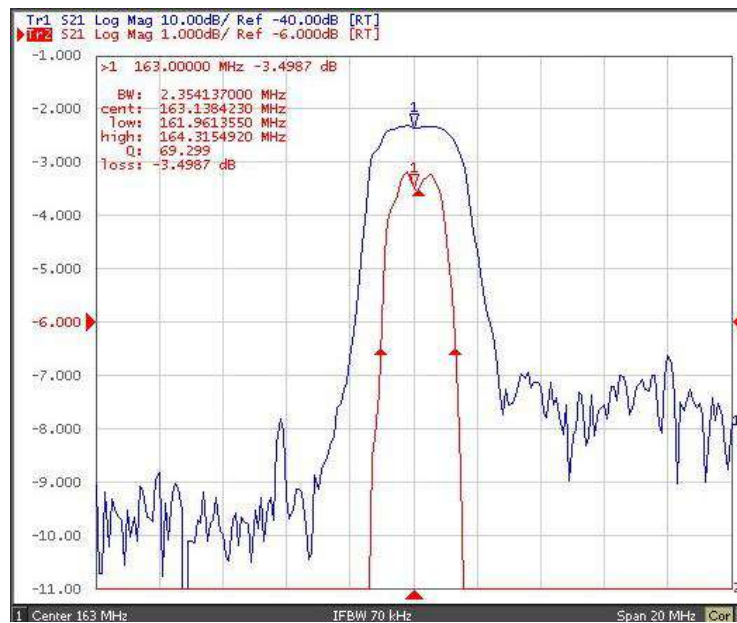
This specification shall cover the characteristics of SAW filter With HD163AN used for the page system.

# 2. ELECTRICAL SPECIFICATION

DC Voltage VDC	10V
AC Voltage Vpp	10V50Hz/60Hz
Operation temperature	-20°C to +60°C
Storage temperature	-45°C to +85°C
RF Power Dissipation	0dBm

## Electronic Characteristics

### 2-1. Typical frequency response

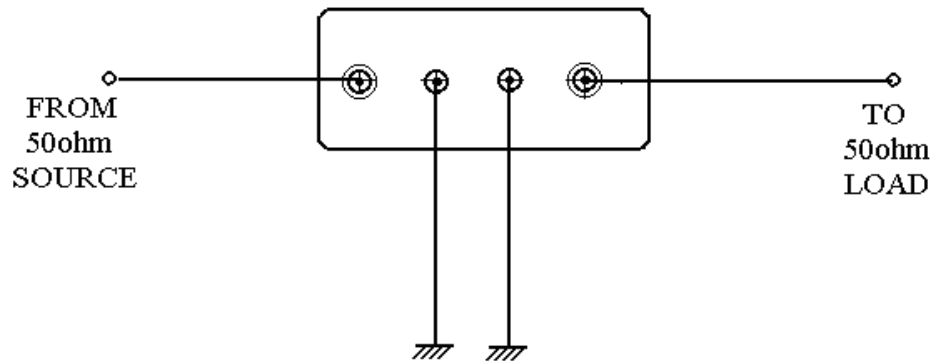


### 2-2. Electrical characteristics

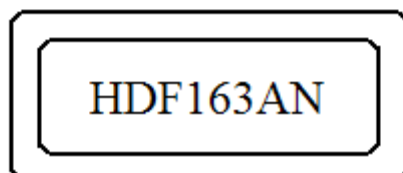
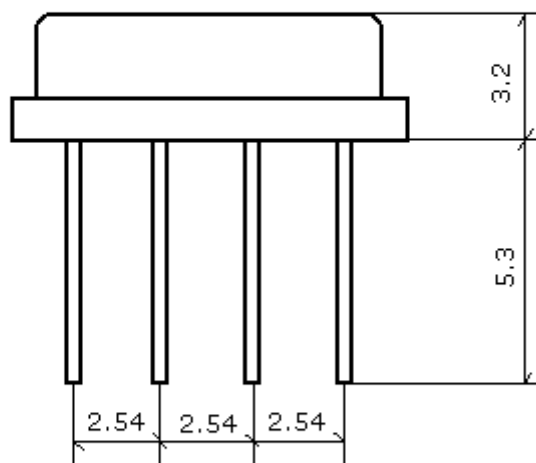
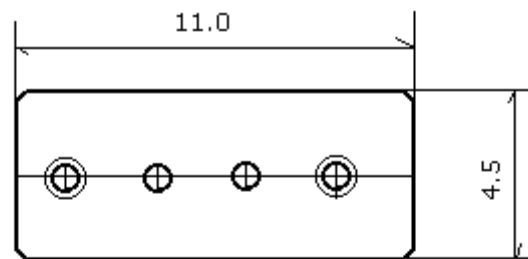
PART NUMBER	HDF163AN	UNIT
NOMINAL CENTERFREQUENCY(Fo)	163.0	MHz
INSERTION LOSS:		
1. Fo-100MHz TO Fo -39.5MHz	45.0Min	dB
2. Fo-39.5MHz TO Fo-10.7MHz	40.0 Min	
3. Fo±1.5 MHz	6.0 Max	
4. Fo+10.7MHz TO Fo+39.5MHz	40.0Min	
5. Fo+39.5 TO +100MHz	45.0 Min	
RIPPLE (WITH PASSBAND)	2.0 Max	dB
INPUT AND OUTPUT IMPEDANCE	50/0	Ω /pF

(Note: Operating temperature Range:-20°C to +60°C)

### 3. TEST CIRCUIT



### 4. DIMENSION



### 5. ENVIRONMENTAL CHARACTERISTICS

#### 5-1 High temperature exposure

Subject the device to +85°C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the

specifications in table 1.

#### 5-2 Low temperature exposure

Subject the device to  $-20^{\circ}\text{C}$  for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in table 1.

#### 5-3 Temperature cycling

Subject the device to a low temperature of  $-40^{\circ}\text{C}$  for 30 minutes. Following by a high temperature of  $+80^{\circ}\text{C}$  for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in table 1.

#### 5-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at  $260^{\circ}\text{C} \pm 10^{\circ}\text{C}$  for  $10 \pm 1$  sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in table 1.

#### 5-5 Solderability

Subject the device terminals into the solder bath at  $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in table 1.

#### 5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in table 1.

#### 5-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in table 1.

#### 5-8 Lead fatigue

##### 5-8-1 Pulling test

Weight along with the direction of lead without an shock 1kg. The device shall satisfy all the initial Characteristics.

##### 5-8-2 Bending test

Lead shall be subject to withstand against  $90^{\circ}\text{C}$  bending with 450g weight in the direction of thickness. This operation shall be done toward both direction. The device shall show no evidence of damage and shall satisfy all the initial electrical characteristics.

## 6. REMARK

#### 6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

#### 6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

#### 6.3 Soldering

Only leads of component may be solded. Please avoid soldering another part of component.